



Material Content Data Sheet



Sales Product Name	BTT6030-2EKA			Issued		29. August 2013		
MA#	MA001146932							
Package	PG-DSO-14-40			Weight*		150.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	2.93	2.93	29330	29330
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		462	
	non noble metal	iron	7439-89-6	1.392	0.92		9248	
	non noble metal	copper	7440-50-8	56.512	37.55	38.53	375525	385351
wire	non noble metal	copper	7440-50-8	1.499	1.00	1.00	9962	9962
encapsulation	organic material	carbon black	1333-86-4	0.165	0.11		1099	
	plastics	epoxy resin	-	7.609	5.06		50560	
	inorganic material	silicondioxide	60676-86-0	74.929	49.80	54.97	497909	549568
leadfinish	non noble metal	tin	7440-31-5	1.226	0.81	0.81	8148	8148
plating	noble metal	silver	7440-22-4	1.417	0.94	0.94	9419	9419
glue	plastics	epoxy resin	-	0.217	0.14		1439	
	noble metal	silver	7440-22-4	1.021	0.68	0.82	6783	8222
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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